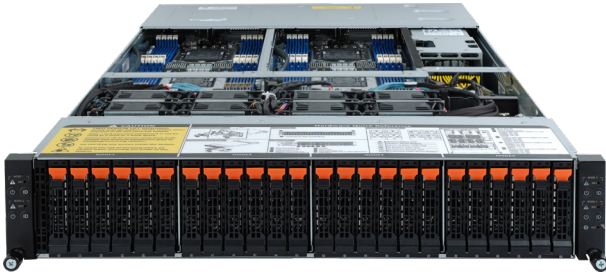


# H262-Z62

## High Density Server - DP 2U 4 Nodes Server



### Features

- 2U - 4 nodes rear access server system
- Dual AMD EPYC™ 7003 Series processors
- 8-Channel RDIMM/LRDIMM DDR4 per processor, 64 x DIMMs
- 8 x 1Gb/s LAN ports (Intel® I350-AM2)
- 4 x Dedicated management ports
- 1 x CMC global management port
- 24 x 2.5" NVMe hot-swappable SSD bays
- 8 x M.2 with PCIe Gen3 x4 interface
- 8 x Low profile PCIe Gen4 x16 expansion slots
- 4 x OCP 2.0 Gen3 x16 mezzanine slots
- Aspeed® AST2500 remote management controller
- 2+0 2200W (240V) 80 PLUS Platinum power supply

### Specification

<b>Dimensions</b>	2U 4 Nodes - Rear access (W440 x H87.5 x D840 mm)	<b>Backplane I/O</b>	24 x ports; Speed and bandwidth: SATA 6Gb/s or SAS 12Gb/s or PCIe Gen3 x4 per port
<b>Motherboard</b>	MZ62-HD0 Rev. 3.0	<b>TPM</b>	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
<b>CPU</b>	AMD EPYC™ 7003 Series processors Dual processors, 7nm technology, cTDP up to 240W Up to 64-core, 128 threads per processor Total 8 x Socket SP3, TDP up to 200W Compatible with AMD EPYC™ 7002 Series processors	<b>Power Supply</b>	2+0 2200W (240V) 80 PLUS Platinum power supply
<b>Chipset</b>	System on Chip	<b>System Management</b>	Aspeed® AST2500 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
<b>Memory</b>	8-Channel DDR4 memory, total 64 x DIMM slots RDIMM/LRDIMM modules up to 128GB supported 3DS RDIMM/LRDIMM modules up to 256GB supported Memory speed: Up to 3200 MHz	<b>OS Compatibility</b>	Windows Server 2016 / 2019 RHEL 8.3 ( x64 ) or later SLES 12 SP5 ( x64 ) / 15 SP2 ( x64 ) or later Ubuntu 18.04.5 LTS (x64) / 20.04 LTS (x64) or later VMware ESXi 6.7 Update3 P03 / 7.0 Update1 or later Citrix Hypervisor 8.2.0 or later
<b>LAN</b>	8 x 1GbE LAN ports (1 x Intel® I350-AM2) 4 x Dedicated management ports 1 x 10/100/1000 CMC global management port	<b>Weight</b>	Net Weight: 28 kg / Gross Weight: 50 kg
<b>Video</b>	Integrated in Aspeed® AST2500 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM	<b>System Fans</b>	8 x 80x80x38mm (16,300rpm)
<b>Storage</b>	24 x 2.5" NVMe hot-swappable SSD bays All storage bays are compatible with SATA devices	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Expansion Slots</b>	8 x Low profile half-length slots with PCIe x16 (Gen4 x16) 4 x OCP 2.0 mezzanine slot with PCIe Gen3 x16 bandwidth 8 x M.2 slots (PCIe Gen3 x4, M-key)	<b>Packaging Content</b>	1 x H262-Z62, 8 x CPU heatsinks, 1 x Rail kit
<b>Internal I/O</b>	Per node: 2 x M.2 slots, 1 x COM header, 1 x TPM header, 1 x BMC SGPIO header, 1 x JTAG BMC header, 1 x PLD header, 1 x Clear CMOS jumper, 1 x IPMB connector	<b>Reference Numbers</b>	Barebone package: 6NH262Z62MR-00 Rev. A00 - Motherboard: 9MZ62HD0NR-00 Rev. 3.0 - Rail kit: 25HB2-AN6103-K0R - CPU heatsink: 25ST1-44320H-A0R/25ST1-44320I-A0R - Back plane board: 9CBPH004NR-00 - NVMe M.2 extension card for Slot_R: 9CMTPO4RNR-00 (optional) - Power Supply: 25EPO-222003-D0S - C19 type power cord 125V/15A (US): 25CP1-018000-Q0R (optional) - C19 type power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional) - C19 type power cord 250V/15A (US): 25CP1-018300-Q0R (optional) - Ring topology kit: 6NH262Z65SR-00-100 (optional)
<b>Front I/O</b>	-		
<b>Rear I/O</b>	Total: 8 x USB 3.0, 4 x VGA, 8 x RJ45, 4 x MLAN, 1 x CMC LAN		

\* All specifications are subject to change without notice. Please visit our website for the latest information.

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